

SHINDENGEN

General Purpose Rectifiers

Dual

S1ZA20

200V 1.1A

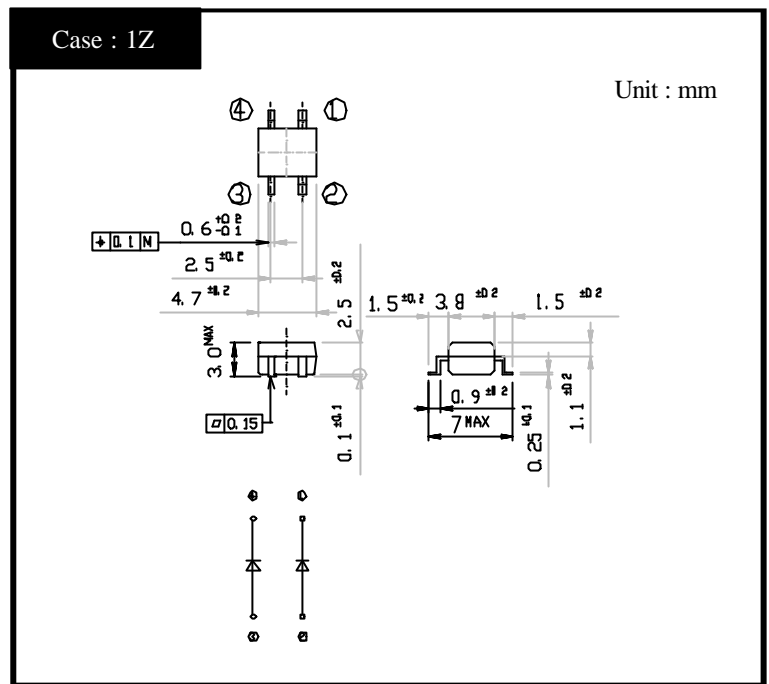
FEATURES

- Small SMT package
- Array
- High reliability with superior moisture resistance
- Applicable to Automatic Insertion

APPLICATION

- Conventional Rectification
- Motor
- Home Appliances, Office Equipment
- Telecommunication, Factory Automation

OUTLINE DIMENSIONS



RATINGS

Absolute Maximum Ratings (If not specified Tl=25)

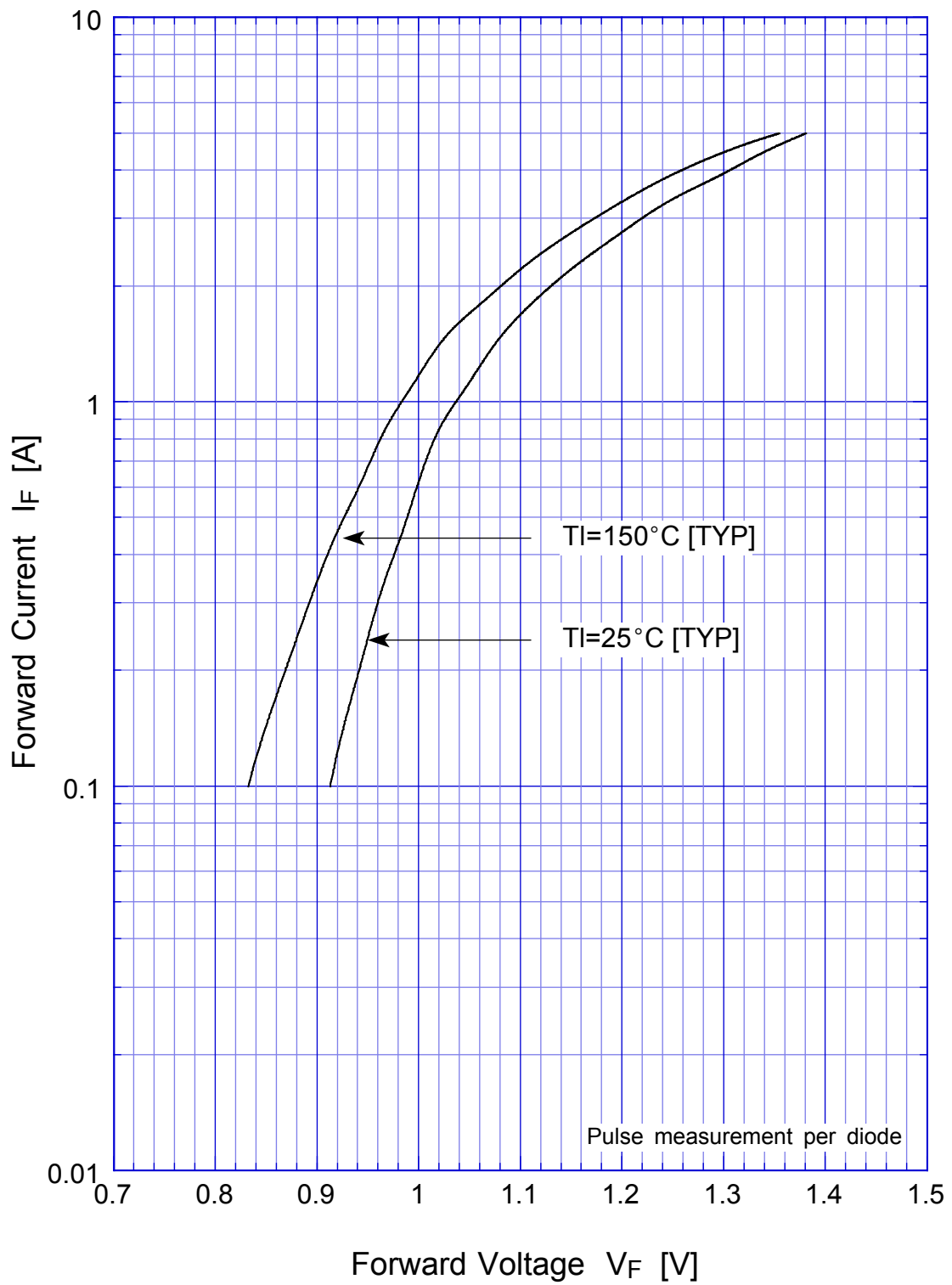
Item	Symbol	Conditions	Ratings	Unit
Storage Temperature	Tstg		-40 ~ 150	
Operating Junction Temperature	Tj		150	
Maximum Reverse Voltage	V _{RM}		200	V
Average Rectified Forward Current	I _O	50Hz sine wave, R-load Ta=25 On alumina substrate 1 element operation	1.1	A
		50Hz sine wave, R-load Ta=25 On alumina substrate 2 element operation	0.8	
		50Hz sine wave, R-load Ta=25 On glass-epoxy substrate 1 element operation	0.9	
		50Hz sine wave, R-load Ta=25 On glass-epoxy substrate 2 element operation	0.63	
Peak Surge Forward Current	I _{FSM}	50Hz sine wave, Non-repetitive 1cycle peak value, Tj=25	30	A

Electrical Characteristics (If not specified Tl=25)

Item	Symbol	Conditions	Ratings	Unit
Forward Voltage	V _F	IF=0.9A, Pulse measurement, Rating of per diode	Max.1.1	V
Reverse Current	I _R	V _R =V _{RM} , Pulse measurement, Rating of per diode	Max.10	μA
Thermal Resistance	ja	junction to ambient On alumina substrate 1 element operation	Max.93	/W
		junction to ambient On alumina substrate 2 element operation	Max.140	
		junction to ambient On glass-epoxy substrate 1 element operation	Max.120	
		junction to ambient On glass-epoxy substrate 2 element operation	Max.186	

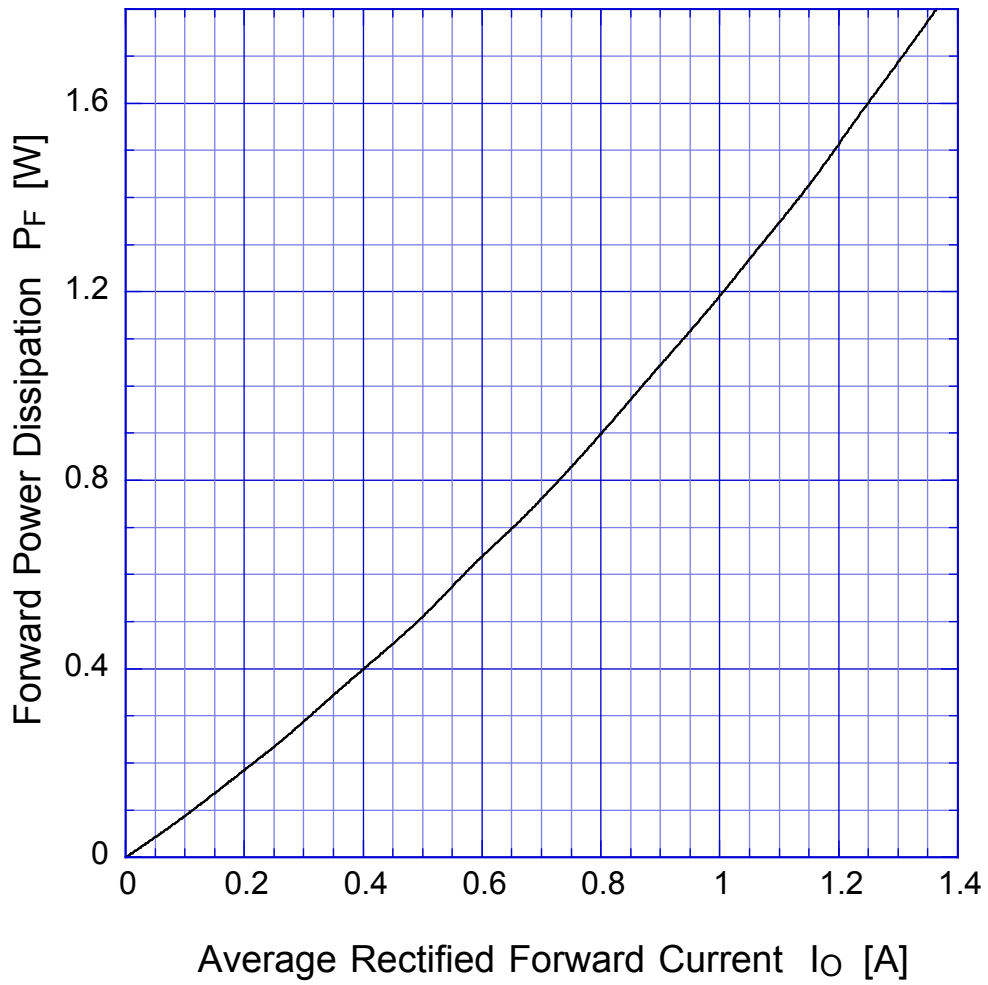
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Forward Voltage



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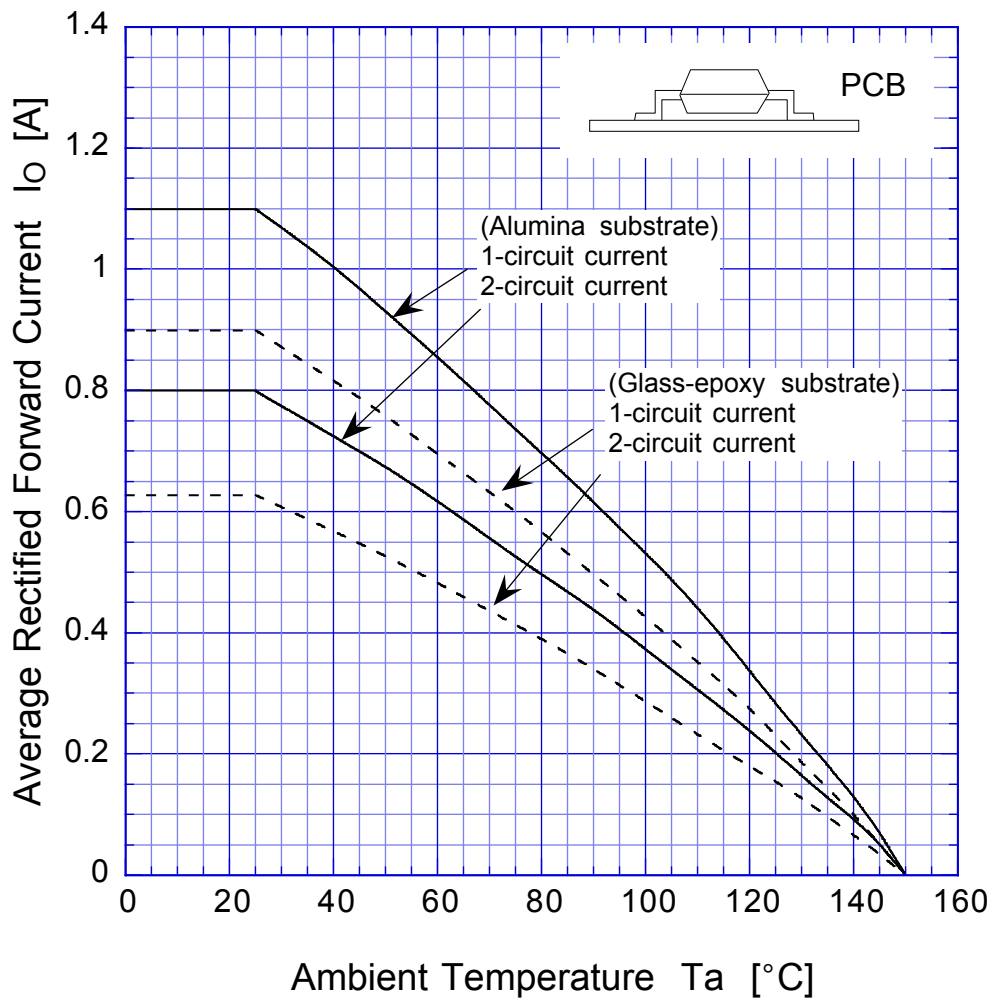
Forward Power Dissipation



$T_j = 150^\circ\text{C}$
Sine wave

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Derating Curve



Alumina substrate
Soldering land 1mm
Conductor layer 20 μ m
Substrate thickness 0.64mm

Glass-epoxy substrate
Soldering land 1mm
Conductor layer 35 μ m

Sine wave
R-load
Free in air

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Peak Surge Forward Capability

